

Amendments to the Claims

Claims 1 and 2 **(Cancelled)**

3. **(Original)** A substrate polishing apparatus comprising:
a rotatable table having a polishing pad for polishing a semiconductor substrate;
a light emission and reception device for emitting measurement light through a through hole formed in said polishing pad to said semiconductor substrate and receiving reflected light from said semiconductor substrate so as to measure a film on said semiconductor substrate; and
a supply passage for supplying a fluid to a path of said measurement light;
wherein said supply passage has an outlet portion detachably mounted on said rotatable table.

Claims 4-33 **(Cancelled)**

34. **(New)** A substrate polishing apparatus according to claim 3, wherein said outlet portion comprises a pipe unit which has a pipe piece.

35. **(New)** A substrate polishing apparatus according to claim 34, wherein said pipe unit has a light-emitting optical fiber constituting said light emission and reception device.

36. **(New)** A substrate polishing apparatus according to claim 34, wherein said pipe unit has a light-receiving optical fiber constituting said light emission and reception device.

37. **(New)** A substrate polishing apparatus according to claim 3, wherein said fluid comprises pure water.

38. **(New)** A polishing apparatus comprising:
a polishing table having a polishing pad for polishing a workpiece, said polishing pad having a hole;

an optical measurement device disposed in said polishing table for emitting measurement light to said workpiece through said hole and receiving reflected light from said workpiece so as to measure a film on said workpiece; and

a supply passage disposed in said polishing table for supplying a fluid to a path of said measurement light;

wherein said supply passage has an outlet portion detachably mounted on said polishing table.

39. **(New)** A polishing apparatus according to claim 38, wherein said outlet portion comprises a pipe unit which has a pipe piece.

40. **(New)** A polishing apparatus according to claim 39, wherein said pipe unit has a light-emitting optical fiber constituting said optical measurement device.

41. **(New)** A polishing apparatus according to claim 39, wherein said pipe unit has a light-receiving optical fiber constituting said optical measurement device.

42. **(New)** A polishing apparatus according to claim 38, wherein said fluid comprises pure water.